半导体设备产品对比图

| Product model | | <u>VF-5900</u> | <u>VF-5700</u> | <u>VF-5300</u> | <u>VF-5100</u> | <u>VF-3000</u> | <u>VF-1000</u> | Mode I 200 | RLA- 3100 | RLA- 1200 | S02- 12-F | VFS- 4000 | Mode I 206A | RLA- 3100-V | RLA- 4106-V | <u>VF-</u> 5300HLP | <u>VF-</u> 5300H | <u>VF-</u> 3000H | <u>VF-</u> 3000HS | CLH Series |
|---------------------|--|----------------|----------------|----------------|----------------|----------------|----------------|---------------|--------------|--------------|--------------|--------------|----------------|----------------|----------------|-----------------------|---------------------|---------------------|----------------------|---------------|
| | | | | | | | | | | | | | | | | | | | | |
| 晶圆大小 | φ300mm | 0 | 0 | - | - | - | 0 | - | - | - | 0 | - | - | - | - | - | - | - | - | 0 |
| | φ200mm | | - | 0 | 0 | 0 | 0 | 0 | 0 | 0 | 0 | - | - | 0 | 0 | 0 | 0 | 0 | 0 | 0 |
| | 高达 ф150mm | <u> </u> | - | 0 | 0 | 0 | 0 | 0 | 0 | 0 | - | - | 0 | 0 | 0 | 0 | 0 | 0 | 0 | 0 |
| | 其他 | - | - | - | - | - | - | 0 | 0 | 0 | - | 0 | 0 | - | - | - | - | - | - | 0 |
| | | | | | | | | | | | | | | | | | | | | |
| 批量大小 [最大存储计数/系统] | φ300mm | 100 | 50 | - | - | - | 25 | - | - | - | 100 | - | - | - | - | - | - | - | - | 25 |
| | φ200mm | | - | 150 | 150 | 50 | 25 | 125 | 1 | 1 | 100 | - | - | 1 | 1 | 100 | 75 | - | 50 | 200 |
| | Up to φ150mm | <u> </u> | - | 200 | 150 | 75 | 50 | 150 | 1 | 1 | - | - | - | 1 | 1 | 100 | 50 | 50 | 75 | 200 |
| | 其他(矩形基板等) | | - | - | - | - | - | - | - | - | - | 40 | 800 | - | - | - | - | - | - | 25 |
| | | | | | | | | | | | | | | | | | | | | |
| 传输系统 | 晶圆 (基板) | 0 | 0 | 0 | 0 | 0 | - | - | 0 | - | 0 | 0 | - | 0 | 0 | 0 | 0 | 0 | 0 | - |
| | 晶盒储料器 | | - | 0 | - | - | - | - | - | - | - | - | - | - | - | 0 | 0 | - | - | - |
| | FOUP 开启器 | 0 | 0 | - | - | - | - | - | - | - | 0 | - | - | - | - | - | - | - | - | - |
| | FOUP 储料器 | 0 | - | - | - | - | - | - | - | - | - | - | - | - | - | - | - | - | - | - |
| | | | | | | | | | | | | | | | | | | | | |
| 系统 | 立式炉管 | 0 | 0 | 0 | 0 | 0 | 0 | - | - | - | - | - | - | - | - | 0 | 0 | 0 | 0 | - |
| | 卧式炉管 | | - | - | - | - | - | 0 | - | - | - | - | 0 | - | - | - | - | - | - | - |
| | 灯退火系统 | <u> </u> | - | - | - | - | - | - | 0 | 0 | - | - | - | 0 | 0 | - | - | - | - | 0 |
| | 洁净烘箱系统 | <u> </u> | - | - | - | - | - | - | - | - | 0 | - | - | - | - | - | - | - | - | - |
| | 大口径立式炉管 | <u> </u> | - | - | - | - | - | - | - | - | - | 0 | - | - | - | - | - | - | - | - |
| | SiC 功率半导体 | - | - | - | - | - | - | - | - | - | - | - | - | 0 | - | 0 | 0 | 0 | 0 | - |
| | | | | • | | | | | | | | | | | | | | | | |
| 半导体 | 退火 | 0 | 0 | 0 | 0 | 0 | 0 | 0 | 0 | - | - | - | - | 0 | 0 | - | 0 | - | 0 | - |
| | 热氧化 | 0 | 0 | 0 | 0 | 0 | 0 | 0 | 0 | 0 | - | - | - | 0 | 0 | - | 0 | - | 0 | - |
| | LPCVD (SiN, Poly-Si (Non-Doped, P-Doped) TEOS, HTO) | 0 | 0 | 0 | 0 | 0 | 0 | 0 | - | - | - | - | - | - | - | - | - | - | - | - |
| | 活化退火 | | | 0 | 0 | 0 | 0 | 0 | - | - | - | - | - | - | - | 0 | - | 0 | - | - |
| | 杂质扩散 | 0 | 0 | 0 | 0 | 0 | 0 | 0 | - | - | - | - | - | - | - | - | 0 | - | 0 | - |
| | 聚酰亚胺固化 | 0 | 0 | 0 | 0 | 0 | 0 | | - | - | 0 | - | - | - | - | - | - | - | - | 0 |
| | 吸杂 | 0 | 0 | 0 | 0 | 0 | 0 | 0 | - | - | - | - | - | - | - | - | 0 | - | 0 | - |
| | 烧结/合金 | 0 | 0 | 0 | 0 | 0 | 0 | 0 | - | - | - | - | - | - | - | - | - | - | - | - |
| | | | | • | | | | | | | | | | | | | | | | |
| SiC 功率半导体 | 活化退火 | · | - | - | - | - | - | - | - | - | - | - | - | - | - | 0 | 0 | 0 | - | - |
| | 热氧化 | | - | 0 | 0 | 0 | 0 | - | - | - | - | - | - | - | - | - | 0 | - | 0 | - |
| | 渗氮/氧氮化 | · | - | - | - | - | - | - | - | - | - | - | - | - | - | - | 0 | - | 0 | - |
| | LPCVD (TEOS) | | - | 0 | 0 | 0 | 0 | - | - | - | - | - | - | - | - | - | - | - | - | - |
| | POA | <u> </u> | - | 0 | 0 | 0 | 0 | - | - | - | - | - | - | - | - | - | 0 | - | 0 | - |
| | 接触退火 | | - | - | - | - | - | - | - | - | - | - | - | 0 | 0 | - | - | - | - | - |
| | | _ | | | | 1 | | | | | 1 | | | | | | | | | |
| MEMS | 热氧化 | 0 | 0 | 0 | 0 | 0 | 0 | - | - | - | - | - | - | - | - | - | - | - | - | - |
| | LPCVD | 0 | 0 | 0 | 0 | 0 | 0 | - | - | - | - | - | - | - | - | - | - | - | - | - |
| | L | _ | 1 | | 1 | | 1 | | 1 | 1 | | 1 | 1 | | | | | 1 | | |
| VCSEL | 热氧化 | <u> </u> | - | 0 | 0 | 0 | 0 | - | - | - | - | - | - | - | - | - | - | - | - | - |
| | 接触退火 | - | - | 0 | 0 | 0 | 0 | - | 0 | 0 | - | - | - | - | - | - | - | - | - | - |
| PV (光伏) | I | | | | | 1 | 1 | | | | 1 | | 1 | | | | | 1 | | |
| | 杂质扩散 | | - | - | - | - | - | 0 | - | - | - | - | 0 | - | - | - | - | - | - | - |
| | 热氧化 | - | - | - | - | - | - | 0 | - | - | - | - | 0 | - | - | - | - | - | - | - |
| | | | | | | | | | | | | | | | | | | | | |
| 封装 | 聚酰亚胺固化 | | 0 | - | - | - | - | - | - | - | 0 | 0 | - | - | - | - | - | - | - | - |
| | 固化 | - | | | | 1 | 1 | | | | 1 | | 1 | | | | | 1 | | |
| FPD | (聚酰亚胺固化) | · | - | - | - | - | - | - | - | - | - | 0 | - | - | - | - | - | - | - | 0 |
| | 活化 | <u> </u> | - | - | - | - | - | - | - | - | - | 0 | - | - | - | - | - | - | - | - |
| | 脱氢 | - | - | - | - | - | - | - | - | - | - | 0 | - | - | - | - | - | - | - | - |
| | 玻璃料烧制 | - | - | - | - | - | - | - | - | - | - | 0 | - | - | - | - | - | - | - | - |
| | 金属接触退火 | | - | - | - | - | - | - | - | - | - | 0 | - | - | - | - | - | - | - | - |
| | | | | | | | | | | | | | | | | | | | | |

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